



Material Content Data Sheet



Sales Product Name	BSC060P03NS3E G			Issued		28. November 2014		
MA#	MA000650868							
Package	PG-TDSON-8-1			Weight*		120.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	2.05	2.05	20502	20502
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		313	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	copper	7440-50-8	37.762	31.21	31.25	312281	312688
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	475	475
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		690	
	plastics	epoxy resin	-	5.923	4.90		48985	
	inorganic material	silicondioxide	60676-86-0	35.707	29.53	34.50	295290	344965
leadfinish	non noble metal	tin	7440-31-5	1.452	1.20	1.20	12005	12005
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1369	1369
solder	noble metal	silver	7440-22-4	0.057	0.05		475	
	non noble metal	tin	7440-31-5	0.046	0.04		380	
	non noble metal	lead	7439-92-1	2.195	1.82	1.91	18154	19009
CLIP plating	noble metal	silver	7440-22-4	1.289	1.07	1.07	10664	10664
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		94	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.36	9.37	93614	93736
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		185	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.43	18.46	184347	184587
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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